

ABRIDGED

**OFFSET DEEP
HOWTER
ETCH PROCESS**

INSTRUCTIONS

	HOWTER DURAPLATE or ordinary anodised plates	HOWTER NORMAPLATE or ordinary grained aluminium	ZINC
CLEANING THE PLATE	Scrub the plate using 1% SULPHURIC ACID then rinse well with water	Scrub the plate using 2½% ACETIC ACID then rinse well with water	Scrub the plate using 2½% ACETIC ACID then rinse well with water
WHIRLER SPEED	90 R.P.M. Apply HOWTER P.C. or SENSITIZED COATING SOLUTION	NORMAPLATE 90 R.P.M. Ordinary Grain Aluminium 70 R.P.M. Apply HOWTER P.C. or SENSITIZED COATING SOLUTION	60 R.P.M. Apply HOWTER P.C. or SENSITISED COATING SOLUTION
EXPOSING	Ensure thoroughly dry and allow plate time to adjust to room conditions before exposing.	Ensure thoroughly dry and allow plate time to adjust to room conditions before exposing.	Ensure thoroughly dry and allow plate time to adjust to room conditions before exposing.
STAGING	Stage out unwanted work with STOPPING OUT SOLUTION or RESISTALL	Stage out unwanted work with STOPPING OUT SOLUTION or RESISTALL	Stage out unwanted work with STOPPING OUT SOLUTION or RESISTALL
DEVELOPING	1-2 Mins.—using DEVELOPER No. 2. 2-5 Mins.—using P.C. DEVELOPER	1-2 Mins.—using DEVELOPER No. 2. 2-5 Mins.—using P.C. DEVELOPER	1-2 Mins.—using DEVELOPER No. 2. 2-5 Mins.—using P.C. DEVELOPER
ETCHING	3 Mins. Maximum using DURAPLATE ETCH	3 Mins. Maximum using 3 in 1 ETCH	2 Mins. Maximum using ZINC ETCH NO. 6
WASHING	Wash with Water Free Alcohol (74 O.P. I.M.S. or HOWTER PROPASOL). Ensure plate thoroughly clean. Dry with Warm Air.	Wash with Water Free Alcohol (74 O.P. I.M.S. or HOWTER PROPASOL). Ensure plate thoroughly clean. Dry with Warm Air.	Wash with Water Free Alcohol (74 O.P. I.M.S. or HOWTER PROPASOL). Ensure plate thoroughly clean. Dry with Warm Air.

FINAL SPOTTING	Use HOWTER SEELIT to stage out any remaining imperfections.	Use HOWTER SEELIT to stage out any remaining imperfections.	Use HOWTER SEELIT to stage out any remaining imperfections.
IMAGE BASE	Spread SE40, PL30 or BLAKLAK over plate with soft cloth. Remove surplus and smooth down with second cloth. Dry with warm air	Spread SE40, PL30 or BLAKLAK over plate with soft cloth. Remove surplus and smooth down with second cloth. Dry with warm air.	Spread SE40, PL30 or BLAKLAK over plate with soft cloth. Remove surplus and smooth down with second cloth. Dry with warm air.
INKING IN	Smooth on INKING IN SOLUTION or P.C. TOPCOAT with lint free stockinette, lightly polish. Powder with French Chalk	Smooth on INKING IN SOLUTION or P.C. TOPCOAT with lint free stockinette, lightly polish. Powder with French Chalk	Smooth on INKING IN SOLUTION or P.C. TOPCOAT with lint free stockinette, lightly polish. Powder with French Chalk
REMOVING STENCIL	Soak in water and scrub with soft bristle or nylon brush. If Stencil obstinate flow with 5% CITRIC ACID. Rinse and scrub off. Gum up.	Soak in water and scrub with soft bristle or nylon brush. If Stencil obstinate flow with 5% CITRIC ACID. Rinse and scrub off. Gum up.	Soak in water and scrub with soft bristle or nylon brush. If Stencil obstinate flow with 5% CITRIC ACID. Rinse and scrub off. Gum up.

FOR COMPLETE DETAILS SEE HOWTER INSTRUCTION MANUAL — FREE ON REQUEST

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